

FIG. 1

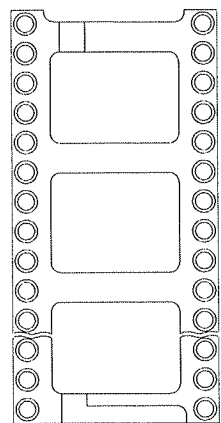


FIG. 2

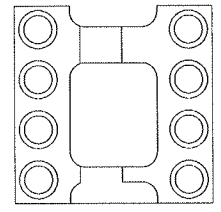
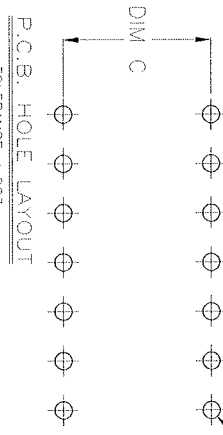
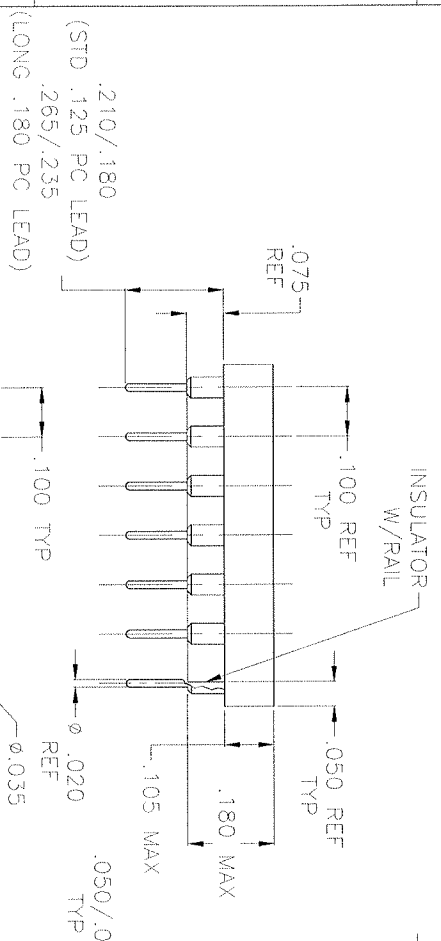
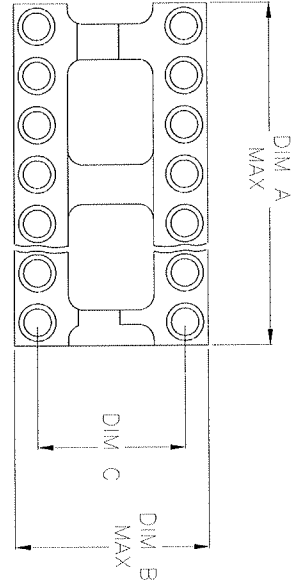


FIG. 3  
(8 POS ONLY)



P.C.B. HOLE LAYOUT  
 TOLERANCE ±.003

▲ MATERIALS

INSULATOR: POLYESTER, UL RATED 94V-0  
 CONTACT: 800 & 1800 SERIES CONTACT: 4 BEAM, COPPER ALLOY, MACHINED (PRELIMINARY VERSION) OR FORMED (ECONOMY)  
 800 SERIES: HIGH RETENTION CONTACT: 4 BEAM, COPPER ALLOY, MACHINED  
 1000 SERIES CONTACT: 8 BEAM, COPPER ALLOY, MACHINED (LOW INSERTION FORCE SERIES)  
 SLEEVE: ALL SERIES, COPPER ALLOY, FORMED  
 ELECTRICAL:  
 CONTACT RESISTANCE: 10 MILLIOHMS MAX  
 CONTACT RATING: 3 AMPS  
 CAPACITANCE: 1.0 pF PER MIL-STD-202, METHOD 308  
 INSULATION RESISTANCE: 500 MΩ MIN. (MIL-STD-202, METHOD 3003.1)  
 DIELECTRIC WITHSTANDING VOLTAGE: 1000 VOLTS (RMS) PER MIL-STD-1344, METHOD 5001.1

▲ MECHANICAL

AFTER INSERTION FORCE: 37 GRAMS AVG (4 BEAM CONTACT), 175 GRAMS AVG (8 BEAM CONTACT), 175 GRAMS AVG (ECONOMY) AND 314 GRAMS AVG (HIGH RETENTION)  
 AFTER WITHDRAWAL FORCE: 15 GRAMS AVG (4 BEAM CONTACT), 63 GRAMS AVG (4 BEAM PREMIUM OR ECONOMY) AND 245 GRAMS AVG (HIGH RETENTION)  
 ENVIRONMENTAL:  
 OPERATING TEMPERATURE: -55°C TO +105°C

▲ PLATING

- ▲ PLATING: 25μ" MIN GOLD OVER 50μ" MIN NICKEL CONTACT WITH 5μ" MIN GOLD OVER 50μ" MIN NICKEL SLEEVE
- ▲ PLATING: 25μ" MIN GOLD OVER 50μ" MIN NICKEL CONTACT WITH 80μ" MIN TIN-LEAD OVER 50μ" MIN COPPER SLEEVE
- ▲ PLATING: 80μ" MIN TIN-LEAD OVER 75μ" MIN COPPER CONTACT WITH 180μ" MIN TIN-LEAD OVER 75μ" MIN NICKEL SLEEVE
- ▲ PLATING: 5μ" MIN GOLD FLASH OVER 50μ" MIN NICKEL CONTACT WITH 80μ" MIN TIN-LEAD OVER 50μ" MIN COPPER SLEEVE
- ▲ PLATING: 75μ" MIN GOLD OVER 50μ" MIN NICKEL CONTACT WITH 80μ" MIN TIN-LEAD OVER 50μ" MIN COPPER SLEEVE
- ▲ PRELIMINARY PART - NOT RELEASED FOR PRODUCTION
- ▲ 088-AGWD-XXX SERIES IS SUPERSEDED BY 506-AGWD-XXX SERIES (REFER TO CONSUMER DRAWING 4937528-2)
- ▲ PLATING: 25μ" MIN GOLD OVER 50μ" MIN NICKEL CONTACT WITH 80μ" MIN WHITE TIN OVER 50μ" MIN COPPER SLEEVE
- ▲ PLATING: 80μ" MIN WHITE TIN OVER 75μ" MIN COPPER CONTACT WITH 180μ" MIN WHITE TIN OVER 75μ" MIN NICKEL SLEEVE
- ▲ PLATING: 5μ" MIN GOLD FLASH OVER 50μ" MIN NICKEL CONTACT WITH 80μ" MIN WHITE TIN OVER 50μ" MIN COPPER SLEEVE
- ▲ PLATING: 75μ" MIN GOLD OVER 50μ" MIN NICKEL CONTACT WITH 80μ" MIN WHITE TIN OVER 50μ" MIN COPPER SLEEVE
- ▲ OBSOLETE PARTS: OBSOLETE CIS STREAMLINED PER D RENAISSANCE SERIES

▲ LEAD STYLE AND TAIL CONFIGURATION

▲ D = PC TAIL STANDARD  
 ▲ AG = INSULATOR  
 ▲ AR = INSULATOR WITH RAUS (ALSO SET FROM THE LENGTH UNDER THE INSULATOR INSIDE THE CONTACT HOLES: .075 REF HIGH & .045 REF WIDE)

REV	DATE	BY	CHKD	DESCRIPTION
1	10/75			INITIAL RELEASE
2	10/75			REVISION
3	10/75			REVISION
4	10/75			REVISION
5	10/75			REVISION
6	10/75			REVISION
7	10/75			REVISION
8	10/75			REVISION
9	10/75			REVISION
10	10/75			REVISION